

Features

- Guard Ring Die Construction for Transient Protection
- High Current Capability
- Low Leakage Current
- Patented Interlocking Clip Design for High Surge Current Capacity
- **Lead Free Finish, RoHS Compliant (Note 4)**
- **"Green" Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: PowerDI®123
- Case Material: Molded Plastic, "Green" Molding Compound
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin Annealed Over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.01 grams (approximate)



Top View

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	40	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	28	V
Average Forward Current	I _{F(AV)}	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	40	A

Thermal Characteristics

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance, Junction to Ambient Air (Note 1)	R _{θJA}	73	—	°C/W
Thermal Resistance, Junction to Soldering Point (Note 2)	R _{θJS}	—	13	°C/W
Operating Temperature Range	T _J	-65 to +125		°C
Storage Temperature Range	T _{STG}	-65 to +150		°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 3)	V _{(BR)R}	40	—	—	V	I _R = 20μA
Forward Voltage	V _F	—	0.52 0.65	0.58 0.7	V	I _F = 1.0A I _F = 2.0A
Leakage Current (Note 3)	I _R	—	—	20 6.0	μA mA	V _R = 40V, T _A = 25°C V _R = 40V, T _A = 100°C
Total Capacitance	C _T	—	28	—	pF	V _R = 10V, f = 1.0MHz

- Notes:
1. Part mounted on Polyimide board with 2 oz., copper, 74mm² pad layout. T_A = 25°C
 2. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 3. Short duration pulse test used to minimize self-heating effect.
 4. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see *EU Directive 2002/95/EC Annex Notes*.

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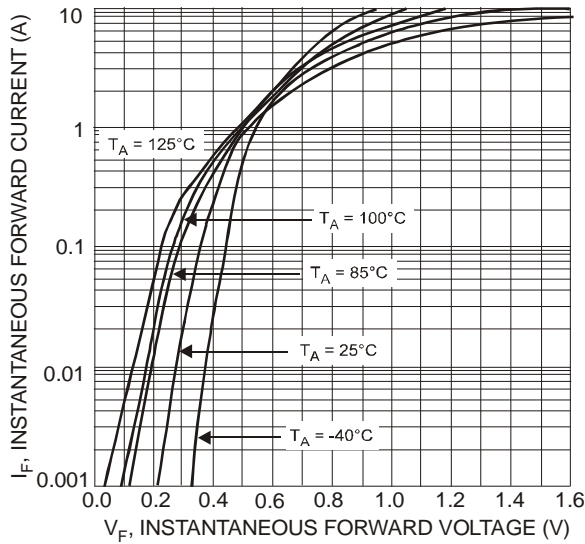


Fig. 1 Typical Forward Characteristics

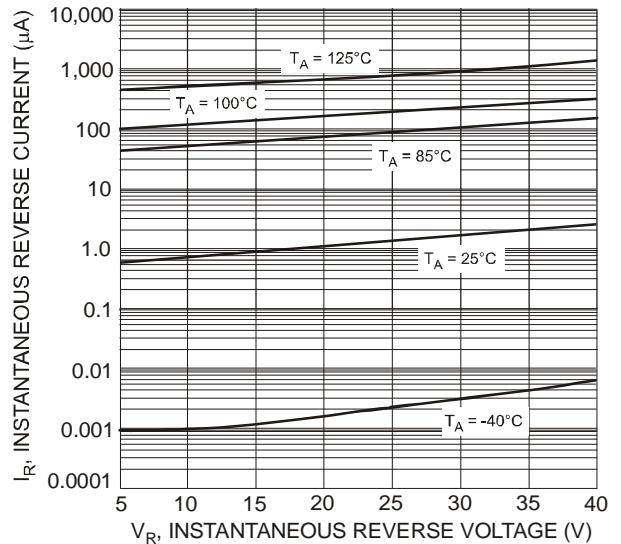


Fig. 2 Typical Reverse Characteristics

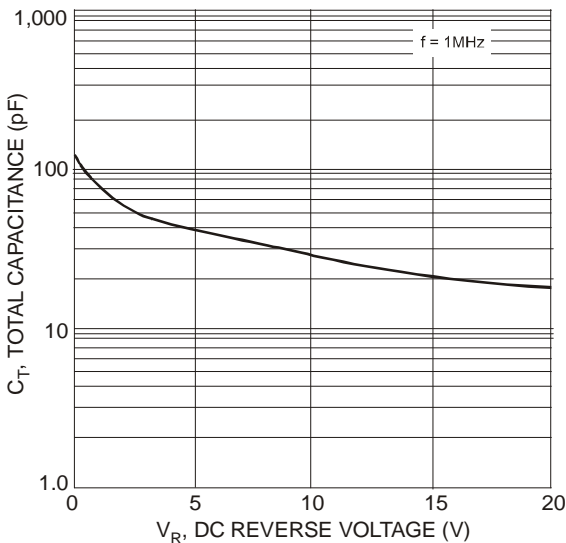


Fig. 3 Total Capacitance vs. Reverse Voltage

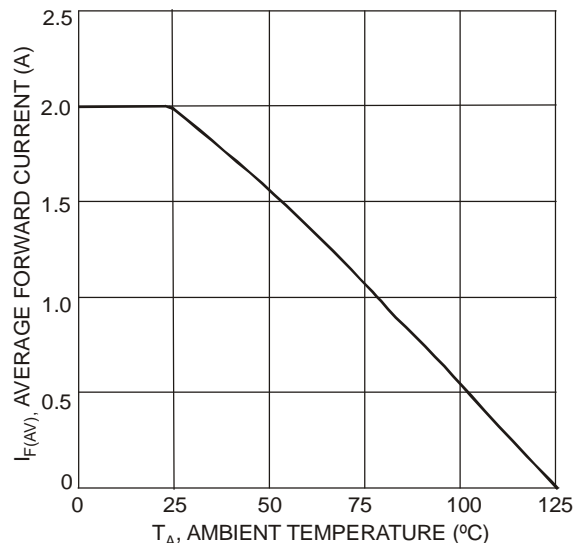


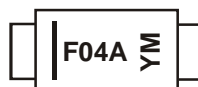
Fig. 4 Forward Current Derating Curve

Ordering Information (Note 5)

Part Number	Case	Packaging
DFLS240-7	PowerDI [®] 123	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



F04A = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: R = 2004)
 M = Month (ex: 9 = September)

Date Code Key

Year	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	P	R	S	T	U	V	W	X	Y	Z

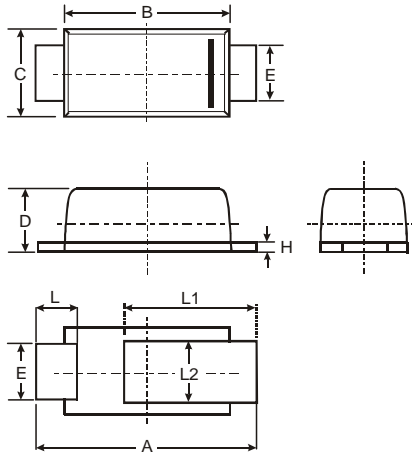
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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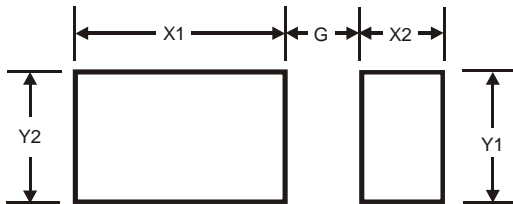
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Package Outline Dimensions



PowerDI [®] 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.55	0.75	0.65
L1	1.80	2.20	2.00
L2	0.95	1.25	1.10
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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